BONDING + SEALING + ENCAPSULATION



TECHNICAL DATASHEET

ergo.® 7411

(ergo.[®] 7407 + ergo.[®] 7409)

Description

ergo.[®] 7411 is a black, fast curing epoxy resin. The adhesive is most appropriate for bonding of metals, ceramic, glass, rubber and hard plastics. It is often used as a repair adhesive (e.g. for carbon fibre reinforced composites), for cable potting or as a structural adhesive in mechanical engineering.

Advantages

- Fast curing
- Excellent adhesion on various substrates (surfaces)
- Black
- Solvent-free, good chemical resistance

Physical properties (liquid product)

Chemical base epoxy resin

Curing System

2-component-system

Mixing ratio (v:v)

1:1 (resin: hardener)

1:00:96.2 (resin: hardener)

Shelf life 24 month at 2 – 30 °C

Viscosity (mixture) acc. to DIN EN 12092 8'000 - 11'000 mPas

Density Mixture 1.1 g/cm³

Colour Resin ergo.® 7407 black

Hardener ergo.® 7409 clear/yellowish

Mixture black

Curing properties

Pot life at 23°C; \sim 5g \sim 3.5 minutes Fixture time at 23°C (> 1 N/mm²) \sim 7 minutes Final strength at 23°C \sim 48 hours

Functional strength (> 10 N/mm²)

at 23°C \sim 60 Minutes at 40°C \sim 35 Minutes at 60°C \sim 10 Minutes at 100°C \sim 2 Minutes

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Physical properties (cured product)

Thermal range - 60 °C up to 100 °C

Glass transition point 52°C

Modulus (DIN EN ISO 178) 1450 MPa

after 7 days at 23°C

Tensile strength (ISO 527 1A) ~ 46 N/mm²

after 7 days at 23°C

Elongation at break (ISO 527 1A) ~ 6 %

after 7 days at 23°C

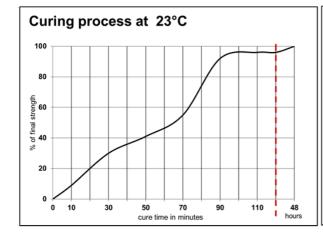
Shore D hardness ~ 75

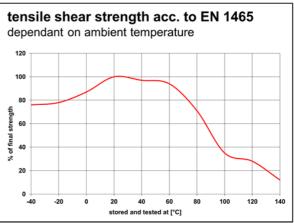
Tensile shear strength acc. to DIN EN 1465

Curing: 16 hours at 40 °C, 24 hours at 23 °C; test temperature: 23 °C; metals corundum blasted / plastics cleaned

Steel> 20 N/mm²Stainless steel> 17 N/mm²Aluminium> 13 N/mm²Brass> 15 N/mm²Copper> 15 N/mm²

GRP, epoxy $\sim 14 \, \text{N/mm}^2$ ABS $\sim 4 \, \text{N/mm}^2$ Polyamide 6 $\sim 4 \, \text{N/mm}^2$ PC $\sim 4 \, \text{N/mm}^2$ PMMA $\sim 3 \, \text{N/mm}^2$ PVC $\sim 4 \, \text{N/mm}^2$





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Thermal conductivity

0.18 W/m·K

Volume resistivity Dielectric strength 8·10¹³ Ω·cm \sim 38.2 kV/mm

Precautions

For your own safety, please refer to the information of the concerned MSDS and for the correct handling the "user instructions".

The information in this data sheet is based on the results of our research and experience. However, the suggestions herein concerning the use, application, and processing of the products (collectively, "the methods") are non-binding recommendations only. It is the user's sole responsibility to determine the suitability and safety of these methods, based on the user's particular purpose in using the products. Before relying on the reliability and safety of any parts that are bonded using the products, it is extremely important that the user test the reliability and safety of the parts that are bonded. Failure to do so could result in serious personal injury. Because of the use of the products are within the purchaser's sole control, Kisling Corporation specifically disclaims all warranties, express or implied, including warranties of merchantability or fitness for a particular purpose, arising from the sale or use of the products described herein. Kisling Corporation specifically disclaims any liability for consequential, incidental, or other damages of any kind, including lost profits. Kisling Corporation's liability for damages shall not exceed the purchase price of the products used.

TIS_7411_e/PC/30.11.2021